g		GE Industri	al Systems	Functional Testing Specification						
	Renewal Ser Louisville, K		LOU-GED-872D432							
	Test Procedure for a LOW VALUE GATE Card									
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Functional test procedure for a Low Value Gate Card

1. SCOPE

1.1 This is a functional testing procedure for a Card.

2. STANDARDS OF QUALITY

2.1 Refer to the current revision of the IPC-A-610 standard for workmanship standards.

3. APPLICABLE DOCUMENTS

- **3.1** The following document(s) shall form part of this specification to the extent specified herein. Unless otherwise indicated, the latest issue shall apply.
 - 3.1.1 D432.DOC Salem test Instruction
 - 3.1.2 838E415 System Schematic

4. ENGINEERING REQUIREMENTS

- **4.1** Equipment Cleaning
 - **4.1.1** Equipment should be clean and free of debris prior to applying power unless performing an initial check. Refer to the local documented procedures for cleaning guidelines.
- 4.2 Equipment Inspection
 - **4.2.1** Equipment should be visually inspected for any defects prior to applying power. This inspection should include the following as a minimum:
 - 4.2.1.1 Wires broken or cracked
 - 4.2.1.2 Terminal strips / connectors broken or cracked
 - **4.2.1.3** Loose wires
 - 4.2.1.4 Components visually damaged
 - 4.2.1.5 Capacitors leaking
 - 4.2.1.6 Solder joints damaged or cold
 - 4.2.1.7 Circuit board burned or de-laminated
 - 4.2.1.8 Printed wire runs burned or damaged

5. EQUIPMENT REQUIRED

5.1 The following equipment is required to perform the process requirements. Equipment may be substituted provided that all accuracy's and test ratios are equivalent or better.

Qty	Reference #	Description
1		Fluke 85 DMM (or Equivalent)
1		-22 VDC Power Supply
1		+30 VDC Power Supply
1		Precision variable DC supply
1		1.5 K Ohm Load resistor (1W)
2		10 K Ohm resistor
1		Dual Operational Amplifier (equiv to LM747) bussed at ±18 VDC
1		±18 VDC Power Supply for Operational Amplifier

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6. <u>TESTING PROCESS</u>

- 6.1 Setup
 - **6.1.1** Connect test per figure 7.1
- 6.2 Testing Procedure
 - **6.2.1** Connect temporary jumper across C1.
 - **6.2.2** Close S1.
 - **6.2.3** Apply -10.0 VDC to pin 10.

6.2.3.1 Note: Current draw at pin 16 of card has been measured at 13mA

- **6.2.4** Voltage out should be +10.0 VDC.
- **6.2.5** Apply -.50 VDC to pin 41.
- **6.2.6** Adjust R17 for output voltage of +10.0 VDC. Open S1.
- **6.2.7** Apply -2.00 VDC to pin 3.
- **6.2.8** Adjust R1 for output of +10.0 VDC.
- **6.2.9** Remove -2.00 VDC from pin 3.
- **6.2.10** Close S1.
- **6.2.11** Apply -20.0 VDC to pin 5.
- **6.2.12** Adjust R13 for output voltage of +1.00 VDC.
- **6.2.13** Apply -10.0 VDC to pin 39.
- **6.2.14** Adjust R14 for output voltage of +10.00 VDC.
- **6.2.15** Apply -10.0 VDC to pin 18.
- 6.2.16 Adjust R8 for output voltage of +10.00 VDC.
- **6.2.17** Open S1.
- **6.2.18** Output voltage should drop then rise slowly back to +10.00 VDC.
- **6.2.19** Close S1.
- **6.2.20** Reduce voltage at pin 18 to -.10 volts.
- **6.2.21** Then remove jumper from C1.
- **6.2.22** Output should integrate to +10.00 VDC in approximately 30 seconds.
- 6.3 ***TEST COMPLETE ***

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7. NOTES

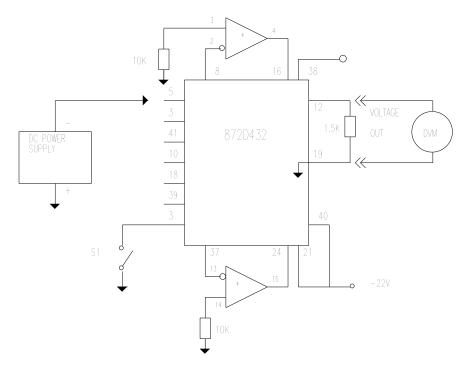


Figure 7.1

7.2 Example Data

INPUTS						OUTPUTS			
Pin 3	Pin 10	Pin 41	Pin 5	Pin 39	Pin 18	Pin 12	TP 2	TP 4	
com	-10.000					10.036	13.672		
com		-0.500				10.000	13.614		
-2.000						10.000	13.603		
com			-20.000			1.000	3.172		
com				-10.000		10.000		13.612	
com					-10.000	10.000		13.613	